

**REMARKS**

Claims 1, 2, 5, 6, and 8-13 are pending in the present application. Claims 1, 2, 5 and 6 are herein amended. No new matter has been presented.

Applicants request entry and consideration of the Amendment filed January 8, 2010, and also request consideration of the following supplemental remarks.

The Advisory Action dated January 25, 2010, states that it is not clear where the limitations added in the Amendment of January 8, 2010 are supported in the original disclosure. Applicants respectfully submit that the specification at, *e.g.*, pages 12-14, describes the process of the present invention as recited in the claims in which the aluminum alloy surface is finely etched to form fine recesses; and then the thermoplastic resin composition is integrally bonded to the surface having the fine recesses by an injection molding process.

Applicants also respectfully submit that Akahoshi (relied on in the Office Action of September 10, 2009 for teaching the recited dipping process in combination with Kallenbach or Haack) does not teach or suggest:

a dipping process in which it is dipped in a 3 to 10% hydrazine monohydrate aqueous solution at 40 to 70°C, said shaped aluminum alloy material having fine recesses with a diameter of 30 to 300 nm on the surface of said shaped aluminum alloy material

as recited in claim 1 and similarly recited in claims 2, 5 and 6.

Akahoshi discloses a method of bonding copper and a resin together with consistently high bonding strength and acid resistance. Akahoshi discloses removing the oxide layer formed

Amendment under 37 C.F.R. §1.114  
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on the surface of copper by using a reducing agent, by a general formula:  $\text{BH}_3 \cdot \text{NHRR}'$ , and including dimethylamine borane and ammonia borane. (Col. 4, lines 12-20.)

However, the reducing agent in Akahoshi does not correspond with a 3 to 10 % hydrazine ( $\text{N}_2\text{H}_4$ ) monohydrate aqueous solution ( $\text{N}_2\text{H}_4\text{H}_2\text{O}$ ) as recited in the present claims. Even if it would have been obvious to modify Kallenbach or Haack to include the processing disclosed in Akahoshi, the modification would not result in the formation of fine recesses as recited in the present claims.

In view of the aforementioned amendments and accompanying remarks, Applicants submit that the claims, as herein amended, are in condition for allowance. Applicants request such action at an early date.

If the Examiner believes that this application is not now in condition for allowance, the Examiner is requested to contact Applicants' undersigned attorney to arrange for an interview to expedite the disposition of this case.

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If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,  
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